



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD053N08N3 G	Issued	11. May 2021
MA#	MA001662026		
Package	PG-TO252-3-313	Weight*	320.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	1.38	1.38	13788	13788
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		459	
	non noble metal	copper	7440-50-8	147.096	45.82	45.88	458302	458899
wire	non noble metal	aluminium	7429-90-5	5.372	1.67	1.67	16738	16738
encapsulation	inorganic material	zinc oxide	1314-13-2	1.360	0.42		4239	
	miscellaneous	miscellaneous	-	6.802	2.12		21194	
	plastics	epoxy resin	-	20.407	6.36		63581	
	inorganic material	silicon dioxide	60676-86-0	107.476	33.49	42.39	334860	423874
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11653	11653
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4426	4437
solder	non noble metal	tin	7440-31-5	0.069	0.02		216	
	noble metal	silver	7440-22-4	0.087	0.03		270	
	non noble metal	lead	7439-92-1	3.305	1.03	1.08	10296	10782
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.98	5.99	59751	59829
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com